

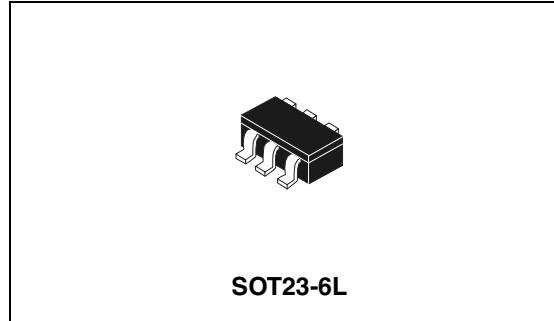
ASD™

TRANSIL™ ARRAY FOR ESD PROTECTION

MAIN APPLICATIONS

Where transient overvoltage protection in ESD sensitive equipment is required, such as:

- Computers
- Printers and other peripherals
- Communications systems
- Cellular phone handsets and accessories
- Other telephone sets
- Consumer Electronics (Set top boxes, DVD players, TV sets)

**FEATURES**

- 5 unidirectional Transil functions
- Minimum breakdown voltage range:
 V_{BR} min. = 17V or 19V
- Peak pulse power (8/20 μ s); 150W
- Tiny leakage current at stand-off voltage:
< 100nA

Table 1: Order Codes

Part Number	Marking
ESDA17-5SC6	175
ESDA19-5SC6	195

DESCRIPTION

The ESDA17/19-5SC6 is a monolithic array designed to protect up to 5 lines against ESD transients.

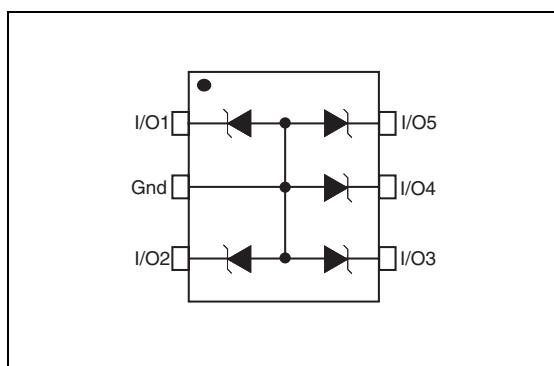
The device is ideal for applications where board space saving is required.

BENEFITS

- High ESD protection level
- High integration
- Suitable for high density boards

COMPLIES WITH THE FOLLOWING STANDARDS:

- IEC61000-4-2 level 4:
15kV (air discharge)
8kV (contact discharge)
- MIL STD 883E-Method 3015-7: class3
25kV (Human Body Model)

Figure 1: Functional Diagram

TM: ASD is a trademark of STMicroelectronics.

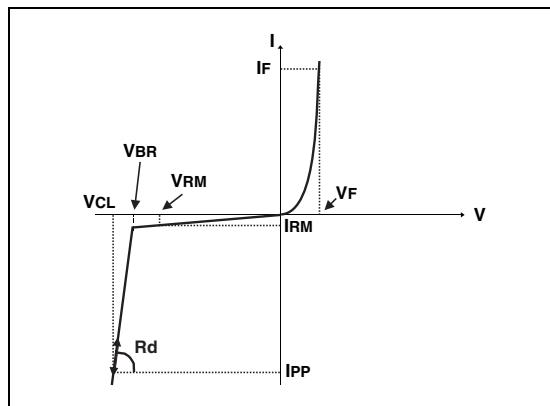
Table 2: Absolute Maximum Ratings ($T_{amb} = 25^\circ C$)

Symbol	Parameter		Value	Unit	
V_{PP}	ESD discharge IEC61000-4-2 air discharge IEC61000-4-2 contact discharge		± 15 ± 8	kV	
P_{PP}	Peak pulse power (8/20μs) (note 1)		T_j initial = T_{amb}	150	W
T_j	Junction temperature			125	°C
T_{stg}	Storage temperature range			-55 to +150	°C
T_L	Maximum lead temperature for soldering during 10 s at 5mm for case			260	°C
T_{op}	Operating temperature range			-40 to +125	°C

Note 1: For a surge greater than the maximum values, the diode will fail in short-circuit.

Table 3: Electrical Characteristics ($T_{amb} = 25^\circ C$)

Symbol	Parameter	
V_{RM}	Stand-off voltage	
V_{BR}	Breakdown voltage	
V_{CL}	Clamping voltage	
I_{RM}	Leakage current	
I_{PP}	Peak pulse current	
αT	Voltage temperature coefficient	
V_F	Forward voltage drop	
C	Capacitance	
R_d	Dynamic resistance	



Types	V_{BR} @ I_R		I_{RM} @ V_{RM}		R_d typ. note 2	αT max. note 3	C typ. 0V bias	V_F @ I_F		
	min.	max.	mA	nA				V	mA	
ESDA17-5SC6	17	19	1	75	14	1	10	33	1.2	10
ESDA19-5SC6	19	21	1	100	15	1	8.5	33	1.2	10

Note 2: Square pulse, $I_{PP} = 15A$, $t_p=2.5\mu s$.

Note 3: $\Delta V_{BR} = \alpha T * (T_{amb} - 25^\circ C) * V_{BR} (25^\circ C)$.

Figure 2: Relative variation of peak pulse power versus initial junction temperature

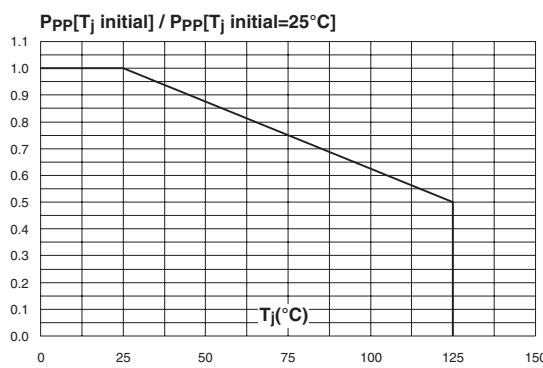


Figure 3: Peak pulse power versus exponential pulse duration

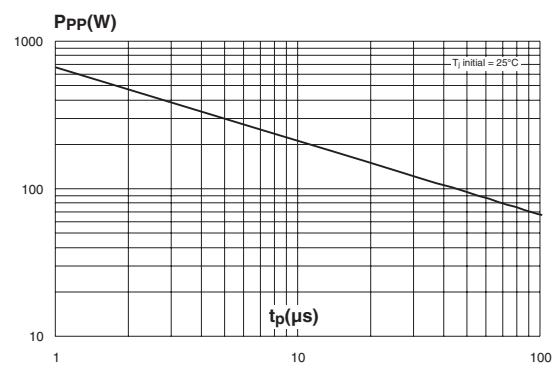


Figure 4: Clamping voltage versus peak pulse current (typical values, rectangular waveform)

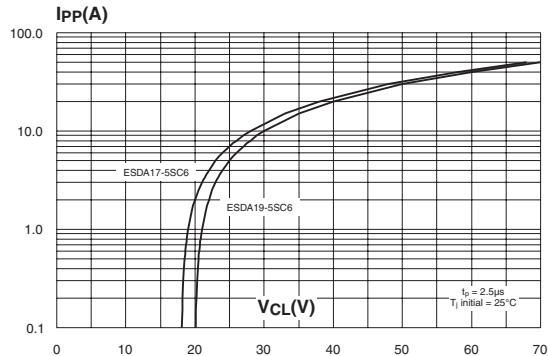


Figure 6: Junction capacitance versus reverse voltage applied (typical values)

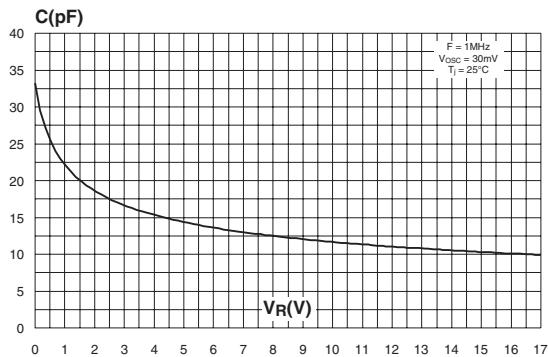


Figure 5: Forward voltage drop versus peak forward current (typical values)

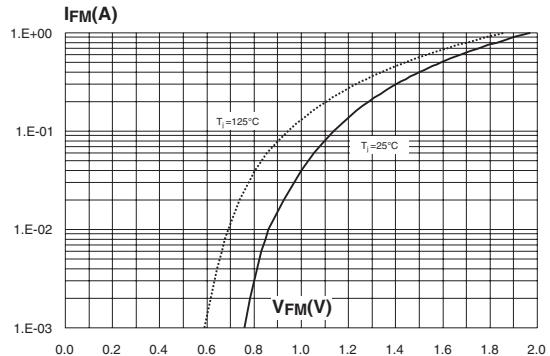


Figure 7: Relative variation of leakage current versus junction temperature (typical values)

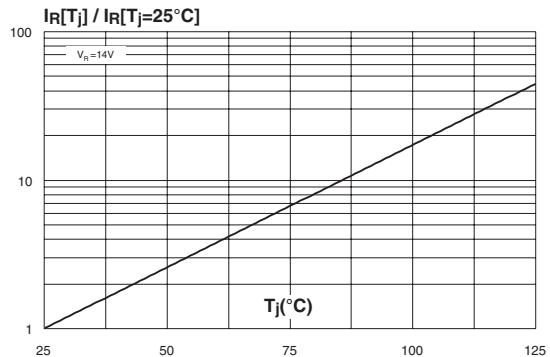


Figure 8: Ordering information scheme

ESDA		17 - 5	SC6	
ESD Array				
Breakdown Voltage (min)				
17 = 17 Volt				
Number of lines protected				
5 = 5 lines				
Package				
SC6 = SOT23-6L				

Figure 9: SOT23-6L Package Mechanical Data

REF.	DIMENSIONS					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	0.90		1.45	0.035		0.057
A1	0		0.10	0		0.004
A2	0.90		1.30	0.035		0.051
b	0.35		0.50	0.014		0.02
C	0.09		0.20	0.004		0.008
D	2.80		3.05	0.110		0.120
E	1.50		1.75	0.059		0.069
e		0.95			0.037	
H	2.60		3.00	0.102		0.118
L	0.10		0.60	0.004		0.024
theta			10°			10°

Figure 10: Foot Print Dimensions (in millimeters)

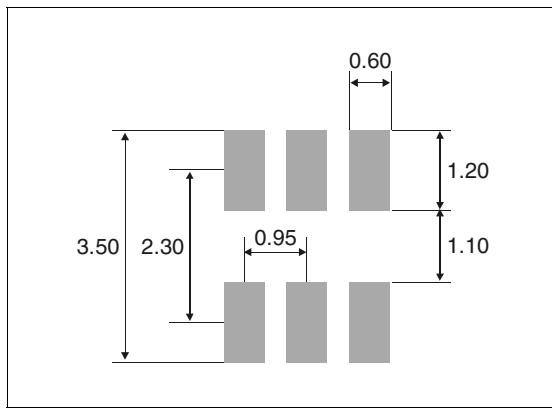


Table 4: Ordering Information

Part Number	Marking	Package	Weight	Base qty	Delivery mode
ESDA17-5SC6	175	SOT23-6L	16.7 mg	3000	Tape & reel
ESDA19-5SC6	195				

Table 5: Revision History

Date	Revision	Description of Changes
Nov-2002	1A	First issue.
4-Nov-2004	2	SOT23-6L package dimensions change for reference "D" from 3.0 millimeters (0.118 inches) to 3.05 millimeters (0.120 inches).

Information furnished is believed to be accurate and reliable. However, STMicroelectronics assumes no responsibility for the consequences of use of such information nor for any infringement of patents or other rights of third parties which may result from its use. No license is granted by implication or otherwise under any patent or patent rights of STMicroelectronics. Specifications mentioned in this publication are subject to change without notice. This publication supersedes and replaces all information previously supplied. STMicroelectronics products are not authorized for use as critical components in life support devices or systems without express written approval of STMicroelectronics.

The ST logo is a registered trademark of STMicroelectronics.
All other names are the property of their respective owners

© 2004 STMicroelectronics - All rights reserved

STMicroelectronics group of companies

Australia - Belgium - Brazil - Canada - China - Czech Republic - Finland - France - Germany - Hong Kong - India - Israel - Italy - Japan -
Malaysia - Malta - Morocco - Singapore - Spain - Sweden - Switzerland - United Kingdom - United States of America
www.st.com

